

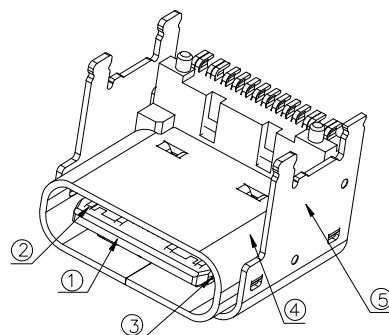
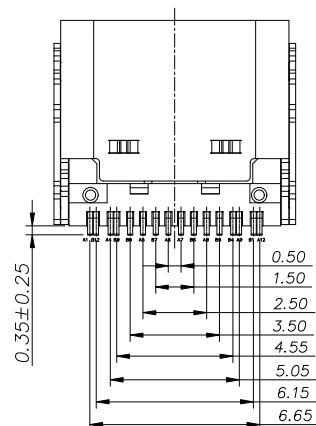
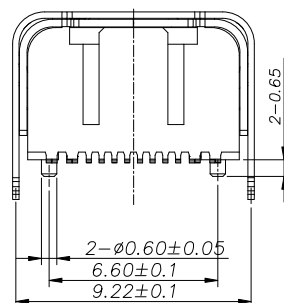
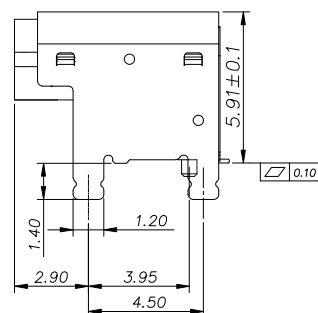
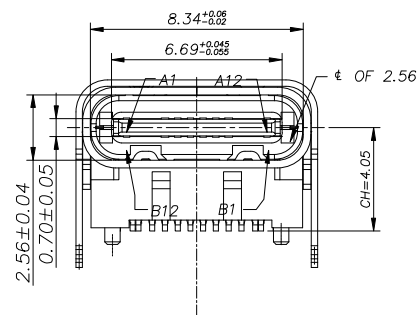
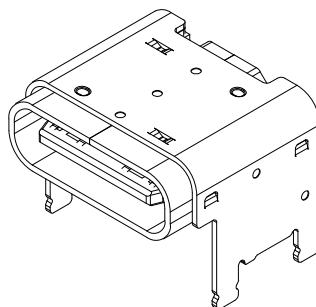
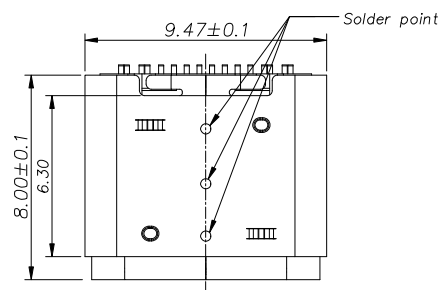
RoHS

MAPX

MODIFICATION

DRW

DATE



NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
- 2.CONTACTS: COPPER ALLOY
- 3.MID PLATE: STAINLESS STEEL
- 4.INSIDE SHELL: STAINLESS STEEL
- 5.OUTSIDE SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

- Ni 50u" MIN. UNDER PLATED OVER ALL.
- Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
- (GOLD PLATING THICKNESS FOLLOW THE P/N)
- GOLD FLASH PLATING ON SOLDER AREA

2-2.INSIDE SHELL OR OUTSIDE SHELL:

- Ni 30u" MIN. UNDER PLATED OVER ALL.

3.MECHANICAL PERFORMANCE,

- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,

4-1. CURRENT RATING:5A

VOLTAGE RATING: 20V

4-2.INSULATION RESISTANCE: 100MΩ MIN

4-3.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

4-4.LOW CONTACT RESISTANCE: INITIAL 40MΩ
AFTER 50MΩ

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -30℃~+80℃.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260℃.

5	OUTER SHELL	SUS304 T=0.25MM	Ni 40u"MIN	1PCS
4	INNER SHELL	SUS304 T=0.30MM	Ni 40u"MIN	1PCS
3	SHIELDING PLATE	SUS301 T=0.15MM	N/A	1PCS
2	CONTACT	C2680 T=0.15MM	Mating area 1u"Au Solder Tails: G/F Underplate: 80u"Min Ni overall	2SET
1	INSERT MOLDING	LCP UL94V-0	BLACK	1PCS
NO.	DESCRIPTION	MATERIAL	REMARKS	

产品图

PRODUCT CHART DWG

公差一览表

TOLERANCE UNLESS OTHERWISE

X.	±0.25	X.	±5.°
.X	±0.15	.X	±2.°
.XX	±0.10	.XX	±1.°
.XXX	±0.05	.XXX	±0.5°

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Easychips Precision Technology (Zhejiang) Co., Ltd.

单位

MM

制图

YANG

制图料号

C918-EC418K2023S40046

比例

1:1

审核

GR

产品名称

TYPE-C3.1母座8.0L/9.47W四

日期

2020-05-22

核准

GT

角法

脚加高2.5CH4.0单排SMT有柱 16PIN

版本

A0

SCALE

CHKD

核淮

VIEW

VER